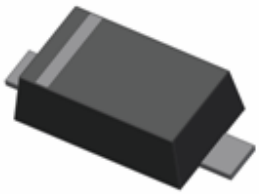
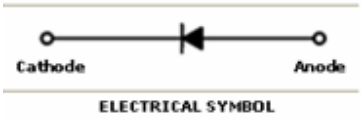
200mW SOD-523 SURFACE MOUNT
Very Small Outline Flat Lead Plastic Package
Schottky Barrier Diode

Green Product



SOD-523 Flat Lead



ELECTRICAL SYMBOL

Absolute Maximum Ratings
T_A = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
P_D	Power Dissipation	200	mW
T_{STG}	Storage Temperature Range	-55 to +125	°C
T_J	Operating Junction Temperature	+125	°C
V_R	Reverse Voltage	30	V
$I_{F(AV)}$	Average Forward Current	200	mA

These ratings are limiting values above which the serviceability of the diode may be impaired.

Specification Features:

- Low Forward Voltage Drop
- Flat Lead SOD-523 Small Outline Plastic Package
- Extremely Small SOD-523 Package
- Surface Device Type Mounting
- RoHS Compliant
- Green EMC
- Matte Tin(Sn) Lead Finish
- Band Indicates Cathode

DEVICE MARKING CODES:

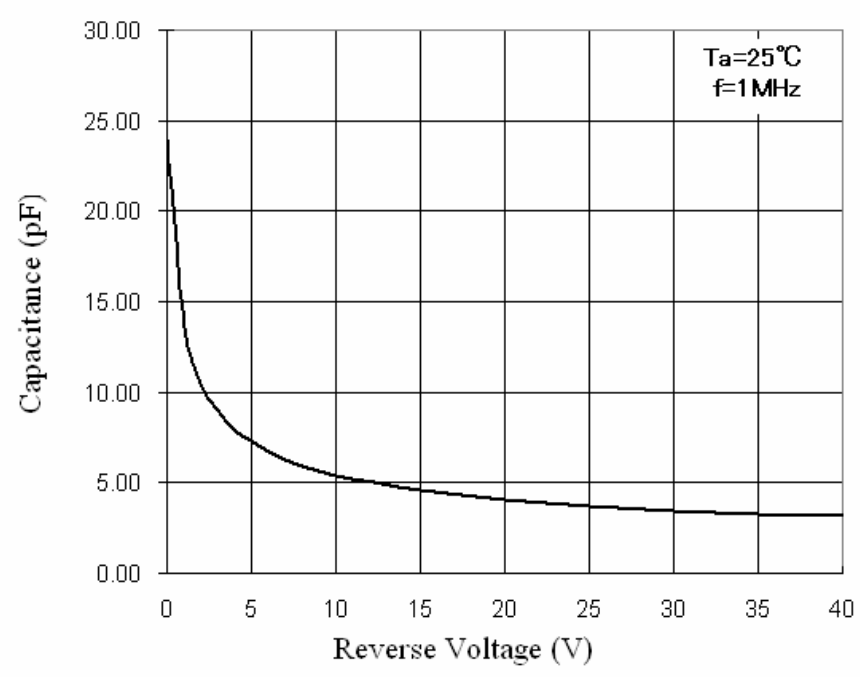
Device Type	Device Marking
TCRB520S-30	1B

Electrical Characteristics
T_A = 25°C unless otherwise noted

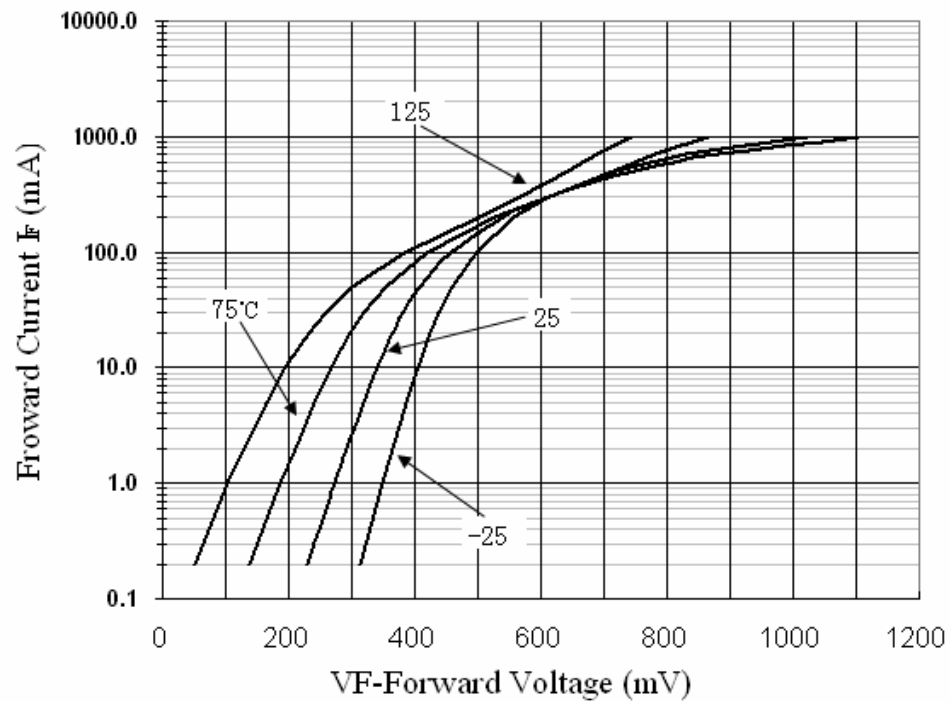
Symbol	Parameter	Test Condition	Limits		Unit
			Min	Max	
B_V	Breakdown Voltage	I_R=500µA	30		Volts
I_R	Reverse Leakage Current	V_R=10V		1	µA
V_F	Forward Voltage	I_F=200mA		0.6	Volts

Typical Performance Characteristics

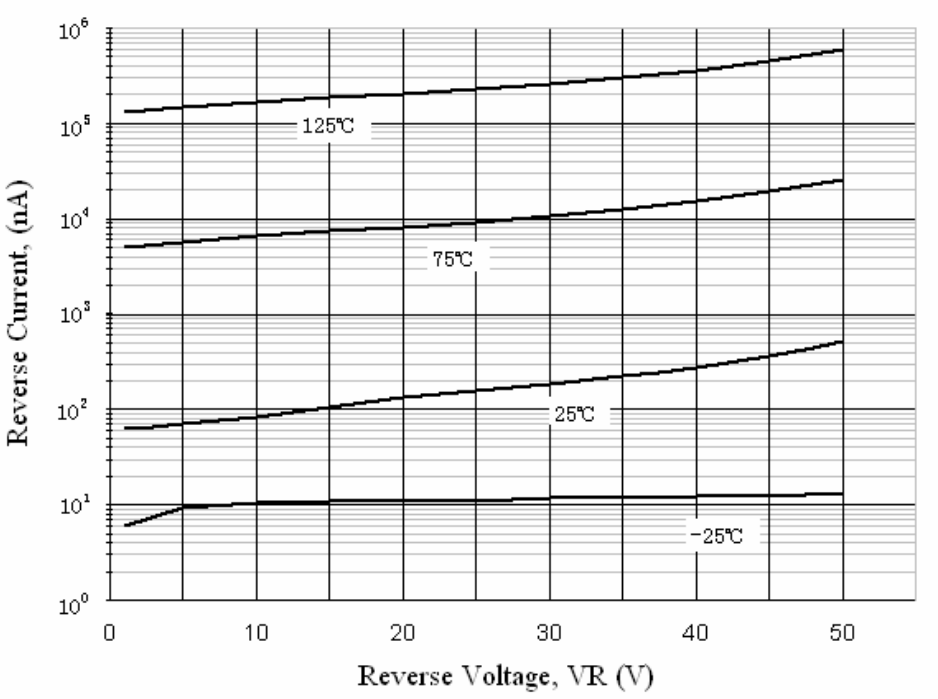
Total Capacitance



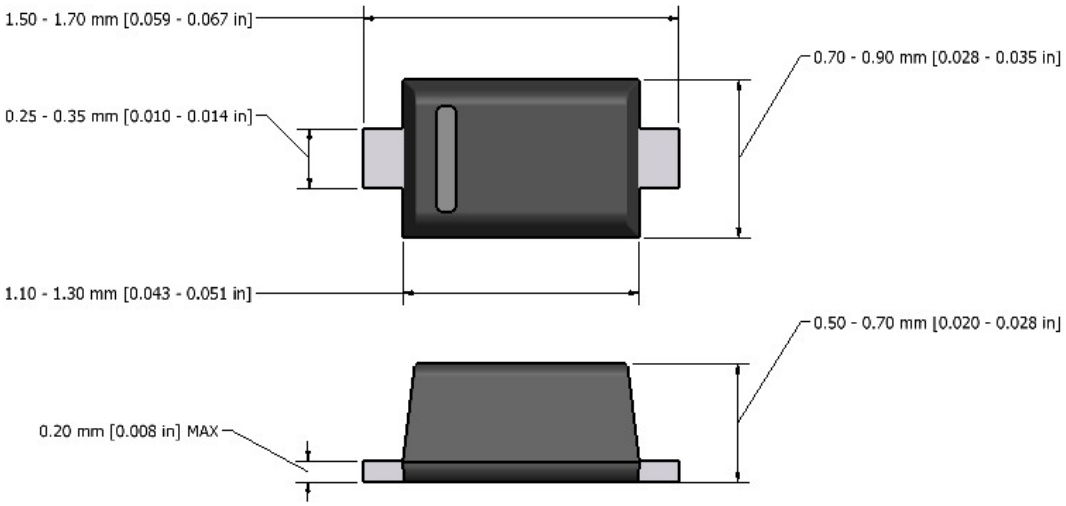
Forward Voltage vs Ambient Temperature



Reverse Current vs Reverse VoltageReverse



Flat Lead SOD-523 Package Outline



This datasheet presents technical data of Tak Cheong's Schottky Barrier Diodes. Complete specifications for the individual devices are provided in the form of datasheets. A comprehensive Selector Guide is included to simplify the task of choosing the best set of components required for a specific application. For additional information, please visit our website http://www.takcheong.com.

Although information in this datasheet has been carefully checked, no responsibility for the inaccuracies can be assumed by Tak Cheong. Please consult your nearest Tak Cheong's sales office for further assistance.

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